

STS5DNE30L

N - CHANNEL 30V - 0.039Ω - 5A SO-8 STripFETTM POWER MOSFET

TYPE	V _{DSS}	R _{DS(on)}	I _D
STS5DNE30L	30 V	< 0.045 Ω	5 A

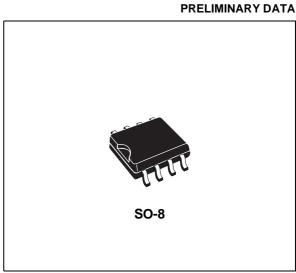
- TYPICAL $R_{DS(on)} = 0.039 \Omega$
- STANDARD OUTLINE FOR EASY AUTOMATED SURFACE MOUNT ASSEMBLY
- LOW THRESHOLD DRIVE

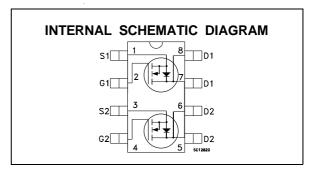
DESCRIPTION

This Power MOSFET is the latest development of STMicroelectronics unique " Single Feature SizeTM " strip-based process. The resulting transistor shows extremely high packing density for low on-resistance, rugged avalanche characteristics and less critical alignment steps therefore remarkable manufacturing reproducibility.

APPLICATIONS

- DC MOTOR DRIVE
- DC-DC CONVERTERS
- BATTERY MANAGMENT IN NOMADIC **EQUIPMENT**
- POWER MANAGEMENT IN PORTABLE/DESKTOP PCs





ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{DS}	Drain-source Voltage (V _{GS} = 0)	30	V
V_{DGR}	Drain- gate Voltage ($R_{GS} = 20 \text{ k}\Omega$)	30	V
V_{GS}	Gate-source Voltage	± 20	V
I _D	Drain Current (continuous) at Tc = 25 °C Single Operation Drain Current (continuous) at T _c = 100 °C Single Operation	5 3.1	A
I _{DM} (•)	Drain Current (pulsed)	20	Α
P _{tot}	Total Dissipation at $T_c = 25$ °C Dual Operation Total Dissipation at $T_c = 25$ °C SinIge Operation	2 1.6	W W

^(•) Pulse width limited by safe operating area

1/5 December 1998

THERMAL DATA

R _{thj-amb}	*Thermal Resistance Junction-ambient Single Operation Dual Operation	78 62.5	°C/W °C/W
Tj Tstg	Maximum Operating Junction Temperature Storage Temperature	150 -55 to 150	°C

(*) Mounted on FR-4 board ($t \le 10 \text{sec}$)

ELECTRICAL CHARACTERISTICS ($T_{case} = 25$ ^{o}C unless otherwise specified) OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source Breakdown Voltage	$I_D = 250 \ \mu A$ $V_{GS} = 0$	30			V
I _{DSS}	Zero Gate Voltage Drain Current (V _{GS} = 0)	$V_{DS} = Max Rating$ $V_{DS} = Max Rating$ $T_c = 125 ^{\circ}C$			1 10	μA μA
I _{GSS}	Gate-body Leakage Current (V _{DS} = 0)	V _{GS} = ± 20 V			± 100	nA

ON (*)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ $I_D = 250 \mu A$	1	1.7	2.5	V
R _{DS(on)}	Static Drain-source On Resistance	$V_{GS} = 10 \text{ V}$ $I_D = 2.5 \text{ A}$ $V_{GS} = 4.5 \text{ V}$ $I_D = 2.5 \text{ A}$		0.039 0.054	0.045 0.065	$\Omega \Omega$
I _{D(on)}	On State Drain Current	$V_{DS} > I_{D(on)} \times R_{DS(on)max}$ $V_{GS} = 10 \text{ V}$	20			Α

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
g _{fs} (*)	Forward Transconductance	$V_{DS} > I_{D(on)} \times R_{DS(on)max}$ $I_D = 2.5 \text{ A}$		6		S
C _{iss} C _{oss} C _{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25 \text{ V}$ f = 1 MHz $V_{GS} = 0 \text{ V}$		TBD		pF pF pF

ELECTRICAL CHARACTERISTICS (continued)

SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{d(on)} t _r	Turn-on Time Rise Time	$V_{DD} = 15 \text{ V}$ $I_{D} = 2.5 \text{ A}$ $R_{G} = 4.7 \Omega$ $V_{GS} = 4.5 \text{ V}$		TBD		ns ns
$egin{array}{c} Q_g \ Q_{gs} \ Q_{gd} \end{array}$	Total Gate Charge Gate-Source Charge Gate-Drain Charge	$V_{DD} = 24 \text{ V}$ $I_D = 5 \text{ A}$ $V_{GS} = 4.5 \text{ V}$		TBD		nC nC nC

SWITCHING OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{r(Voff)} t _f t _c	9	$V_{DD} = 24 \text{ V}$ $I_D = 5 \text{ A}$ $R_G = 4.7 \Omega$ $V_{GS} = 4.5 \text{ V}$		TBD		ns ns ns

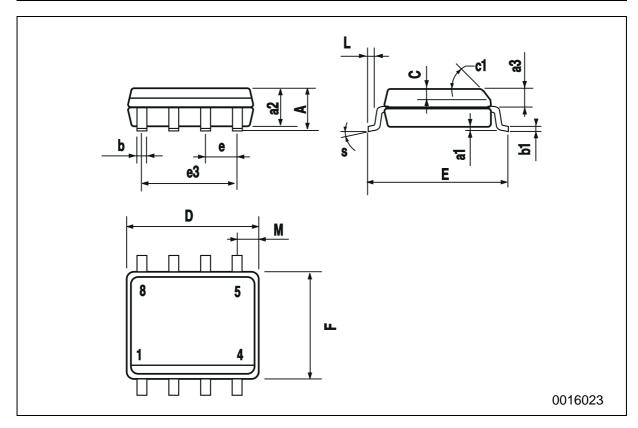
SOURCE DRAIN DIODE

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
I _{SD} I _{SDM} (•)	Source-drain Current Source-drain Current (pulsed)				5 24	A A
V _{SD} (*)	Forward On Voltage	$I_{SD} = 5 A V_{GS} = 0$			1.2	V
t _{rr}	Reverse Recovery Time	$I_{SD} = 5 \text{ A}$ di/dt = 100 A/ μ s V _r = 20 V T _i = 150 °C		TBD		ns
Q_{rr}	Reverse Recovery	, , , , , , , , , , , , , , , , , , , ,				nC
I _{RRM}	Charge Reverse Recovery Current					Α

^(*) Pulsed: Pulse duration = 300 μs, duty cycle 1.5 %
(•) Pulse width limited by safe operating area

SO-8 MECHANICAL DATA

DIM.		mm			inch	
DIIVI.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А			1.75			0.068
a1	0.1		0.25	0.003		0.009
a2			1.65			0.064
a3	0.65		0.85	0.025		0.033
b	0.35		0.48	0.013		0.018
b1	0.19		0.25	0.007		0.010
С	0.25		0.5	0.010		0.019
c1			45	(typ.)		
D	4.8		5.0	0.188		0.196
Е	5.8		6.2	0.228		0.244
е		1.27			0.050	
e3		3.81			0.150	
F	3.8		4.0	0.14		0.157
L	0.4		1.27	0.015		0.050
М			0.6			0.023
S			8 (r	nax.)		



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